

KEY FEATURES

- Wide Input range: 3.4V to 60V
- 3A Continuous Output Current
- High-Efficiency, Synchronous Mode Control
- 230mΩ/50mΩ Internal Power MOSFETs
- Adjustable Switching Frequency: 300kHz to 2.2MHz
- 180° Out-of-Phase SYNCO Clock
- 4μA Quiescent Current (I_Q)
- Low 30μA Operating Quiescent Current From 24V_{IN} to 5V_{OUT}
- Low 1.5μA Shutdown Current
- FB Voltage Tolerance: 0.8V ±1.25% over the Full Temperature Range (-40°C to +125°C)
- Selectable Pulse Frequency Modulation (PFM) Mode or Forced Continuous Conduction Mode (FCCM) during Light-Load Operation
- Precision Enable and Power Good (PG)
- Output 0.9ms Soft-Start
- Low-Dropout (LDO) Mode Operation
- V_{IN} Under-Voltage Lockout (UVLO)
- Cycle-by-Cycle Over-Current Protection (OCP)
- Short-Circuit Protection (SCP) with Hiccup
- Thermal Shutdown
- Available in a QFN-12 (2.5mmx3mm) Package

APPLICATIONS

- Telecommunications Infrastructure
- Lamps and LEDs
- Motor Controls
- Industrial Power Systems
- IoT sensor

GENERAL DESCRIPTION

The AWK4573 is a 3A synchronous step-down, DC-DC converter, which integrated a 230mΩ high-side MOSFET and a 50mΩ low-side MOSFET to provide a high efficiency solution.

The AWK4573 provides a wide input range, from 3.4V to 60V, which is highly adaptable to a wide variety of step-down applications within Industrial and telecom environments. With a shutdown current as low as 1.5μA, this device is also an ideal option for battery-powered applications.

The AWK4573 uses peak-current-mode control (with the integrated compensation), Pulse Frequency Modulation (PFM) mode scheme for excellent stability, output accuracy and transient response.

Implemented Internally, soft-start function and slope compensation circuits reduce design time and allows the device to be used with the minimum the external components. The support for a close-to-100% duty cycle and Low-Dropout (LDO) Mode operation enables the device to withstand automotive cold cranking.

The AWK4573 features power good function, undervoltage lockout (UVLO), cycle-by-cycle over-current protection, hiccup mode short-circuit protection, thermal shutdown.

This device is available in a compact, 12-lead, 2.5mm × 3mm QFN package.

TYPICAL APPLICATION

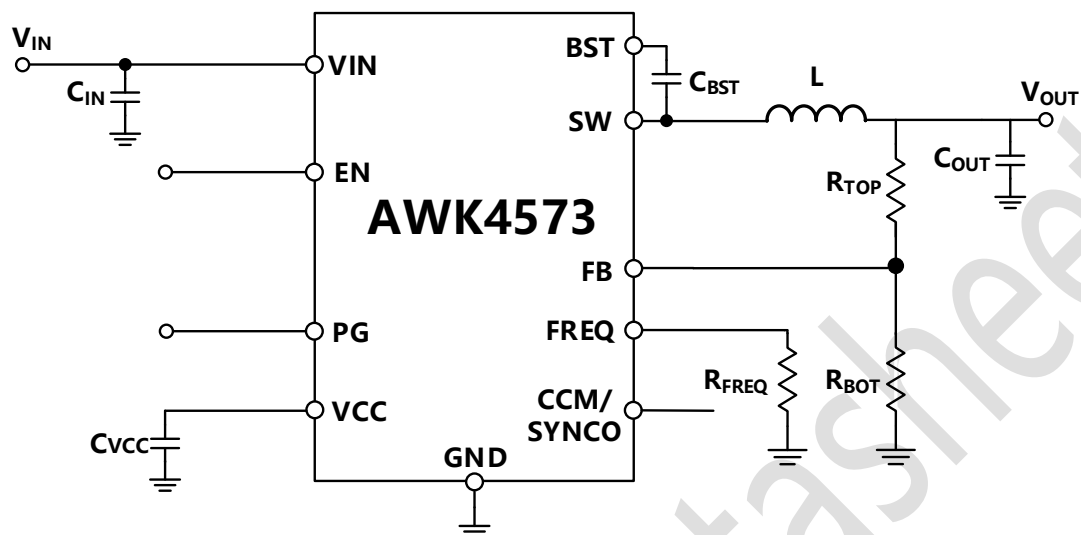


Figure 1. AWK4573

TABLE OF CONTENTS

Key Features.....	1
Applications	1
General Description.....	1
Typical Application	2
Table of Contents	3
Pin Configuration	5
Specifications.....	7
Absolute Maximum Ratings	7
Recommended Operating Conditions.....	7
Electrostatic Discharge (ESD)	8
ESD Caution.....	8
Thermal Resistance	8
Electrical Specifications	9
Typical Characteristics	11
Typical Performance Characteristics.....	13
Functional Block Diagram	22
Product Overview.....	23
Peak Current Control.....	23
Operating Modes	23
Precision Enable and Shutdown.....	24
Internal VCC Regulator	24
Bootstrap Circuitry.....	24
Synchronous Output (SYNCO).....	24
Switching Frequency	24
Spread Spectrum Modulation.....	25
Internal Soft Start (SS) and Prebias Soft Start.....	25
Power Good Function	26
Undervoltage Lockout (UVLO).....	26
Over Current Protection And Short Circuit Protection.....	26
Negative Current Limit Protection	27
Thermal Shutdown.....	27
Low-Dropout (LDO) Mode.....	27
Typical Application Circuit.....	28
Application Information.....	28
Input Capacitor Selection	28
Output Voltage setting.....	29

Inductor Selection	29
Output Capacitor Selection.....	30
Setting VIN Under-voltage Lockout (UVLO)	31
Bootstrap (BST) Resistor and Capacitor selection	31
Layout Recommendation.....	32
Package Information	33
Package Top marking	33
Tape and Reel Box Information.....	33
Tape and Reel Information	34
Package Outlines.....	35
Ordering Information.....	36
Revision History	37

Pin No.	Pin Name	Type ¹	Description
8	VIN	P, I	Input Power Supply Pin. Connect the power supply to this pin and connect a bypass capacitor between this pin and GND pin.
9, 10	NC	–	No connect. To improve thermal and EMI performance, connect NC pins to Ground.
11	CCM/SYNCO	O	Mode Selection/Synchronous output. To force the converter into continuous conduction mode (CCM), connect the CCM/SYNCO pin to GND via a 10kΩ to 300kΩ resistor. Float this pin to force the converter into Pulse Frequency Modulation (PFM) mode under light-load conditions. CCM/SYNCO is also a synchronization output pin that can output a 180° out-of-phase clock to other devices.
12	EN	I	Precision Enable Pin. Drive the EN pin above 1.47V to turn the converter on; float EN or drive it below 1.14V to turn the converter off. An extra resistor divider can be set to create the UVLO.

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Min	Max	Unit
V_{IN}	-0.3	60	V
V_{SW}	-0.3	60	V
V_{BST}	-0.3	$V_{SW}+6V$	V
All other pins	-0.3	6	V
Continuous Power Dissipation		2.08	W
Junction temperature	-40	150	°C
Storage temperature	-65	150	°C
Lead temperature (soldering, 10sec.)		260	°C

Absolute maximum ratings are rated under room temperature, unless otherwise noted.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

RECOMMENDED OPERATING CONDITIONS

Table 3.

Parameters	Min	Typ	Max	Unit
Operating Temperature	-40		125	°C
Continuous Supply Voltage (V_{IN})	3.4		60	V
Output Voltage (V_{OUT})	1% of V_{IN}		98% of V_{IN}	V
Load Current Range	0		3	A
Junction Temperature (T_J)	-40		150	°C

ELECTROSTATIC DISCHARGE (ESD)

Table 4. ESD Rating

Parameters	Description	Rating	Unit
HBM	Human Body Model ANSI/ESDA/JEDEC JS-001-2024 Classification, Class: 2	±2000	V
CDM	Charged Device Mode ANSI/ESDA/JEDEC JS-002-2025 Classification, Class: C3	±2000	V
Latch-Up	JESD78F.02-2023 Temperature Classification, Class: I.A	±200	mA

ESD CAUTION



Electrostatic Discharge Sensitive Device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

THERMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Close attention to PCB thermal design is required.

Table 5. Thermal Resistance

Item ¹²	Description	Value	Unit
θ_{JA}	Junction-to-ambient thermal resistance	60	°C/W
θ_{Jc}	Junction-to-case (top) thermal resistance	13	°C/W

(1) The package thermal impedance is calculated in accordance to JESD 51-7.

(2) Thermal Resistances were simulated on a 4-layer, JEDEC board.

ELECTRICAL SPECIFICATIONS

Limits apply over the recommended operating junction temperature range of -40°C to $+125^{\circ}\text{C}$, unless otherwise stated. Minimum and Maximum limits are specified through test, design or statistical correlation. Typical values represent the most likely parametric norm at $T_J = 25^{\circ}\text{C}$, and are provided for reference purposes only. Unless otherwise stated the following conditions apply: $V_{IN} = 24\text{V}$. V_{OUT} is converter output voltage.

Table 6.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
INPUT SUPPLY AND UNDER-VOLTAGE LOCKOUT (UVLO)						
Quiescent Supply Current	I_Q	No load, $V_{FB} = 0.85\text{V}$, PFM		4	10	μA
Shutdown Supply Current	I_{SD}	$V_{EN} = 0\text{V}$		1.5	5	μA
V_{IN} UVLO Rising Threshold	$V_{IN_UV_RISING}$				3.4	V
V_{IN} UVLO Threshold Hysteresis	$V_{IN_UV_HYS}$			0.5		V
OUTPUT AND REGULATION						
FB Reference Voltage	V_{REF}		0.79	0.8	0.81	V
FB Input Current	I_{FB}	$V_{FB} = 0.8\text{V}$			20	nA
SWITCHES AND FREQUENCY						
High-Side on Resistance	$R_{DS(ON)_HS}$	$V_{BST} - V_{SW} = 3.5\text{V}$	100	230	500	$\text{m}\Omega$
Low-Side on Resistance	$R_{DS(ON)_LS}$		20	50	90	$\text{m}\Omega$
SW Leakage current	I_{SW_LKG}	$V_{EN} = 0\text{V}$, $V_{SW} = 0\text{V}$ or 60V		0.1	10	μA
Switching frequency	f_{SW}	$\text{RFREQ} = 76.8\text{k}\Omega$	380	400	420	kHz
		$\text{RFREQ} = 28\text{k}\Omega$	900	1000	1100	kHz
		$\text{RFREQ} = 12.1\text{k}\Omega$	2000	2150	2300	kHz
SW Minimum on Time ¹	T_{ON_MIN}			40		ns
SW Minimum off Time ¹	T_{OFF_MIN}			100		ns
POWER GOOD (PG)						
PG Current Sink	V_{PG_SINK}	Sink 4mA			300	mV
PG Deglitch Time	t_{PG_DELAY}	Rising Edge		80		μs
		Falling Edge		80		μs
PG Leakage Current	I_{PG_LKG}			10	100	nA
PG Rising Threshold (V_{REF})	PG_{RISING}	VFB Rising	87	90	93	%
		VFB Falling	104	108	112	%
PG Falling Threshold (V_{REF})	$PG_{FALLING}$	VFB Falling	80	84	88	%
		VFB Rising	112	116	120	%

¹ Derived from bench characterization. Not tested in production.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
ENABLE (EN)						
EN Rising Threshold	V_{EN_RISING}		1.4	1.47	1.54	V
EN Falling Threshold	$V_{EN_FALLING}$		1.09	1.14	1.19	V
EN Threshold Hysteresis	V_{EN_HYS}			330		mV
EN Input Current	I_{EN}	$V_{EN} = 2V$		0.68		μA
EN Turn-off Delay	t_{EN_DELAY}		5			μs
BOOTSTRAP(BST)						
(BST-SW) UVLO				2.25	2.5	V
SOFT START (SS) AND VCC						
Soft-Start Time	t_{SS}	10% to 90%		0.9		ms
VCC Regulator	V_{CC}	$I_{CC} = 0mA$	3.4	3.55	3.7	V
PROTECTIONS						
Peak Current Limit Threshold	I_{PEAK_LIMIT}	20% duty cycle	4.2	5.4	6	A
Valley Current Limit Threshold	I_{VALLEY_LIMIT}		3			A
Zero-Current Detection (ZCD) Threshold	I_{ZCD}	PFM		0.15		A
Negative current limit threshold	I_{NEG_LIMIT}	FCCM	0.5	1.2	2	A
Thermal Shutdown	T_{SD}			170		$^{\circ}C$
Thermal Shutdown Hysteresis	T_{SD_HYS}			25		$^{\circ}C$

TYPICAL CHARACTERISTICS

$V_{IN} = 24V$, $T_J = -40^{\circ}C$ to $+125^{\circ}C$, unless otherwise noted.

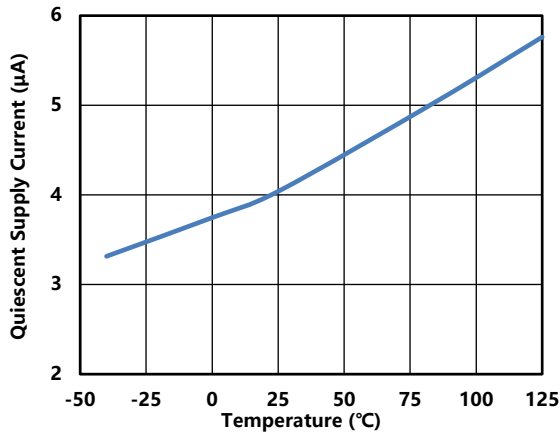


Figure 3. Quiescent Supply Current vs. Temperature

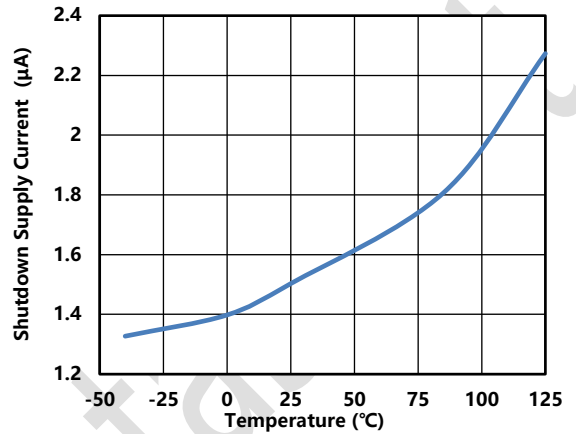


Figure 4. Shutdown Current vs. Temperature

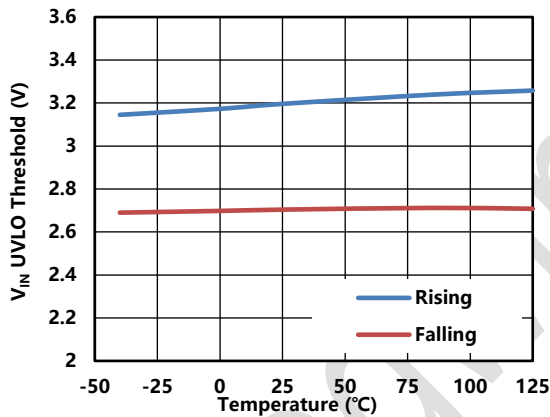


Figure 5. VIN UVLO Threshold vs. Temperature

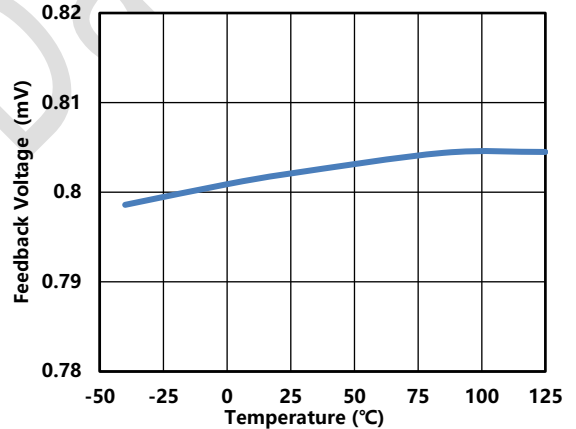


Figure 6. Feedback Voltage vs. Temperature

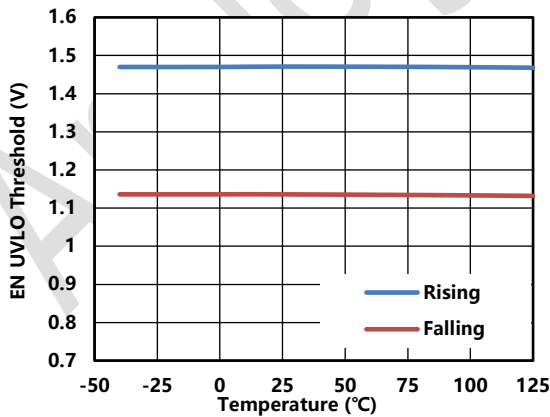


Figure 7. EN Threshold vs. Temperature

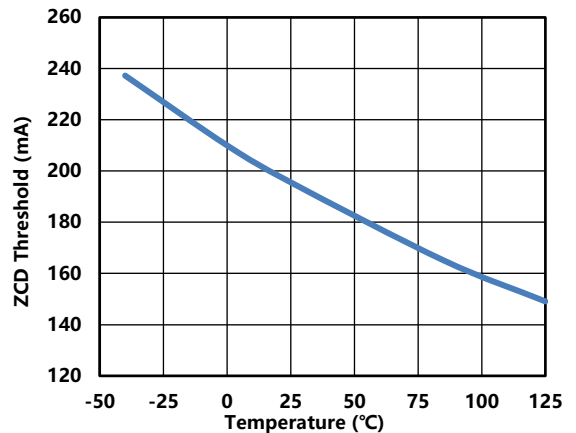


Figure 8. ZCD Threshold vs. Temperature

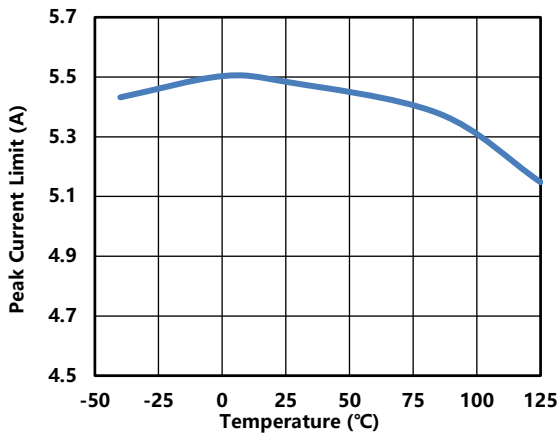


Figure 9. Peak Current Limit vs. Temperature

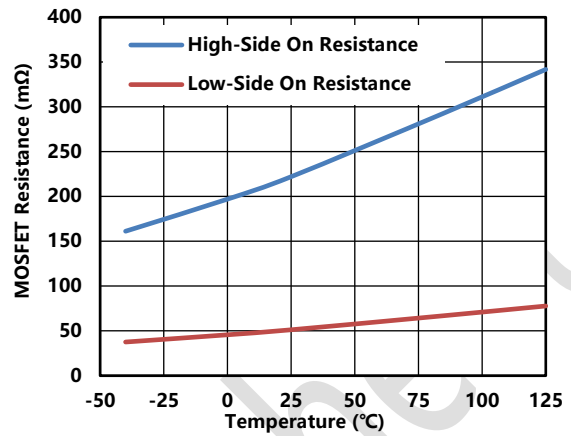


Figure 10. MOSFET Resistance vs. Temperature

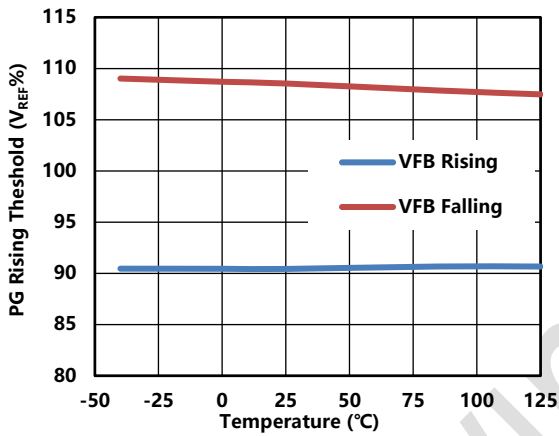


Figure 11. PG Rising Threshold vs. Temperature

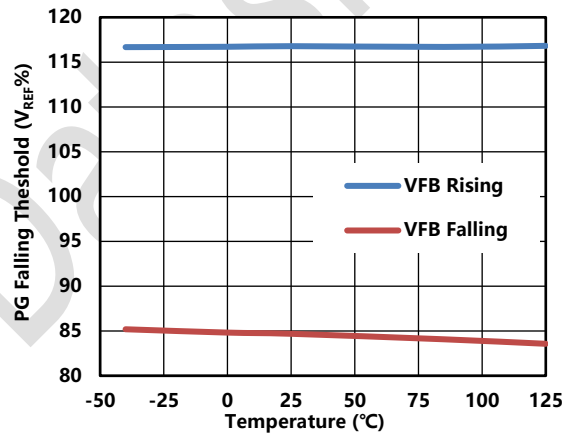


Figure 12. PG Falling Threshold vs. Temperature

TYPICAL PERFORMANCE CHARACTERISTICS

$V_{IN} = 24V$, $V_{OUT} = 5V$, $L = 15\mu H^{(1)}$, $f_{SW} = 400kHz$, $T_A = 25^\circ C$, unless otherwise noted.

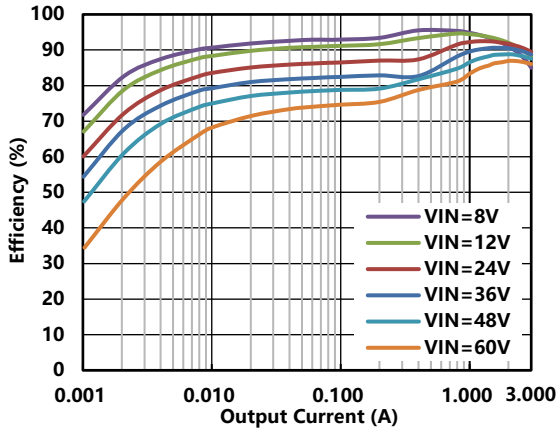


Figure 13. Efficiency (PFM, $f_{sw} = 400kHz$, $L = 15\mu H$)

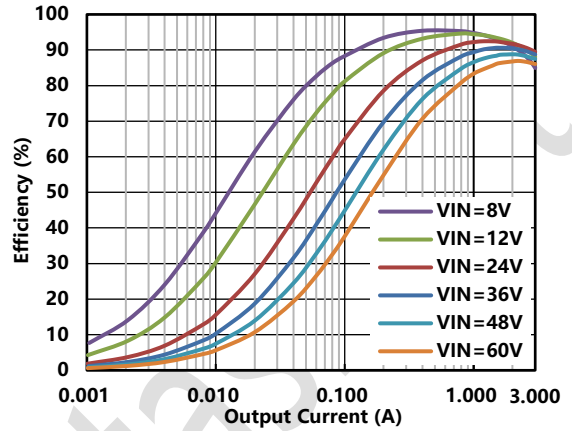


Figure 14. Efficiency (FCCM, $f_{sw} = 400kHz$, $L = 15\mu H$)

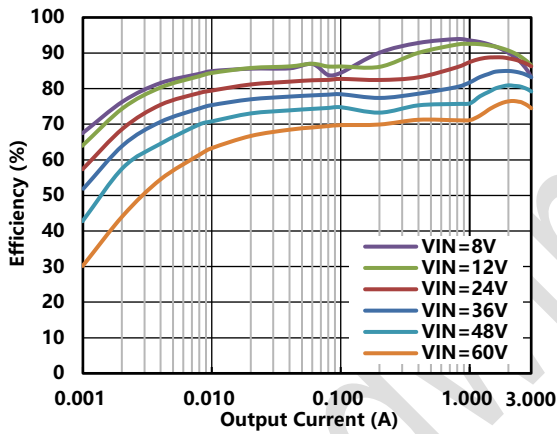


Figure 15. Efficiency (PFM, $f_{sw} = 1MHz$, $L = 10\mu H^{(2)}$)

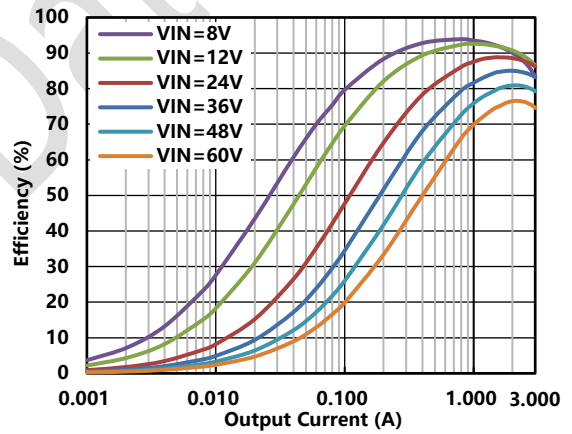


Figure 16. Efficiency (FCCM, $f_{sw} = 1MHz$, $L = 10\mu H$)

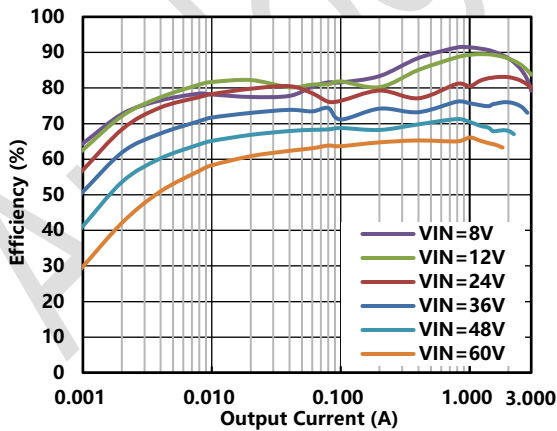


Figure 17. Efficiency (PFM, $f_{sw} = 2.2MHz$, $L = 4.7\mu H^{(2)}$)

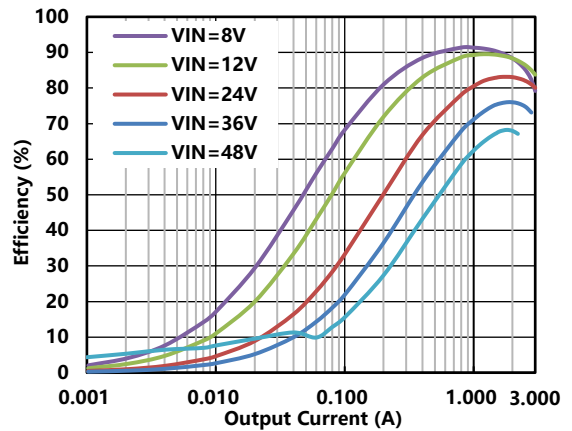


Figure 18. Efficiency (FCCM, $f_{sw} = 2.2MHz$, $L = 4.7\mu H$)

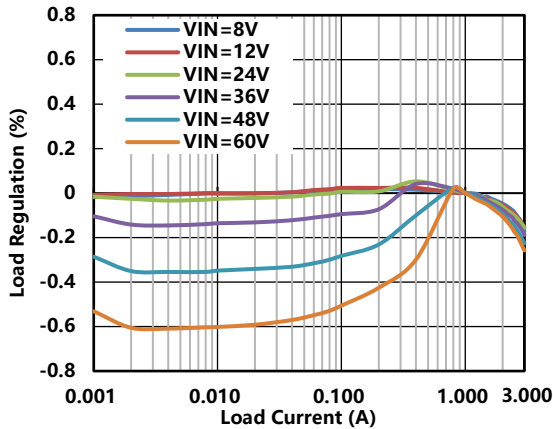


Figure 19. Load Regulation (PFM)

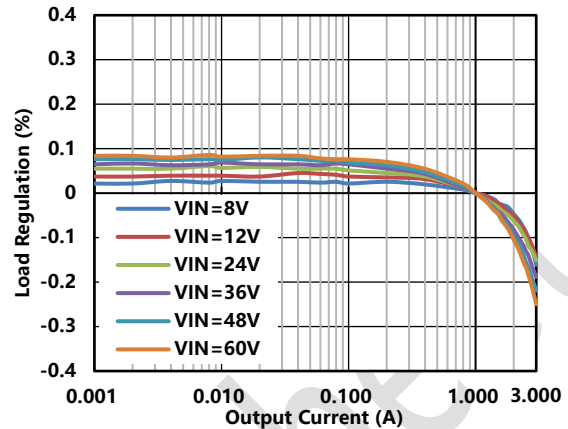


Figure 20. Load Regulation (FCCM)

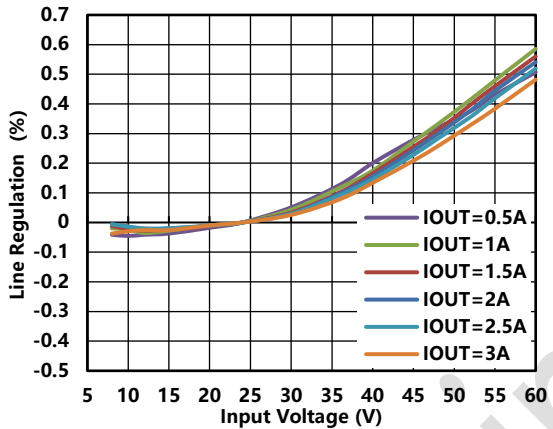


Figure 21. Line Regulation (PFM)

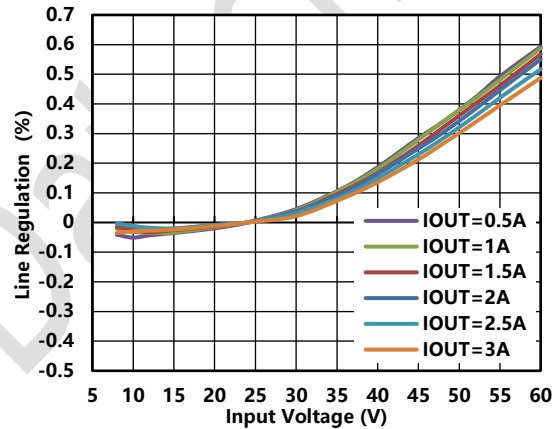


Figure 22. Line Regulation (FCCM)

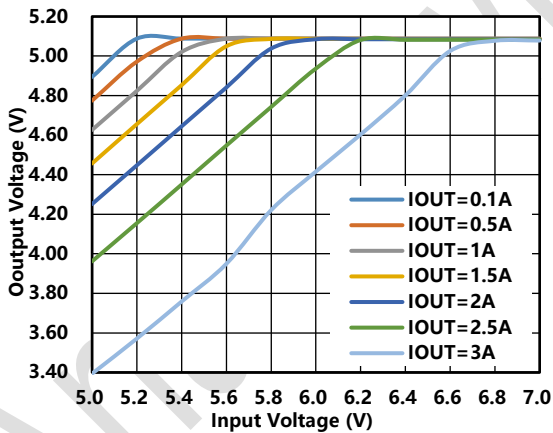


Figure 23. Output Voltage vs. Input Voltage, Dropout Performance

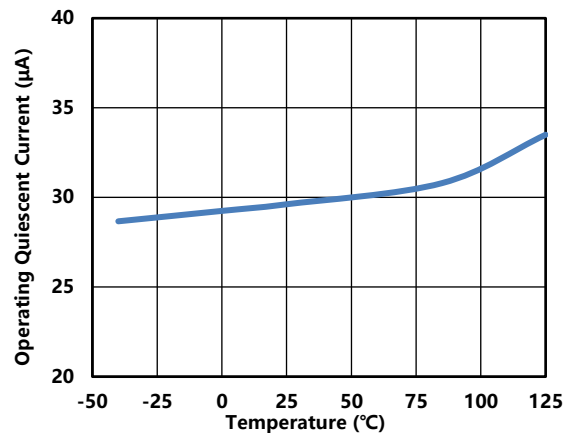


Figure 24. Operating Quiescent Current vs. Temperature

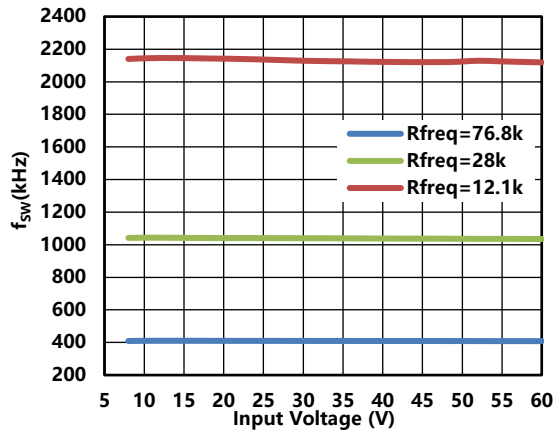


Figure 25. Switching Frequency vs. Input Voltage⁽⁴⁾

Note:

- (1) Inductor PN: XAL6060-153MEB/C; DCR=39.8mΩ.
- (2) Inductor PN: XAL6060-103MEB/C; DCR=27mΩ.
- (3) Inductor PN: XAL6060-472MEB/C; DCR=13.1mΩ.
- (4) $V_{IN} < 30V$ is recommended due to high temperature rise at 2.2MHz.

TYPICAL PERFORMANCE CHARACTERISTICS(CONTINUED)

$V_{IN} = 24V, V_{OUT} = 5V, L = 15\mu H^{(1)}, f_{SW} = 400kHz, T_A = 25^\circ C$, unless otherwise noted.

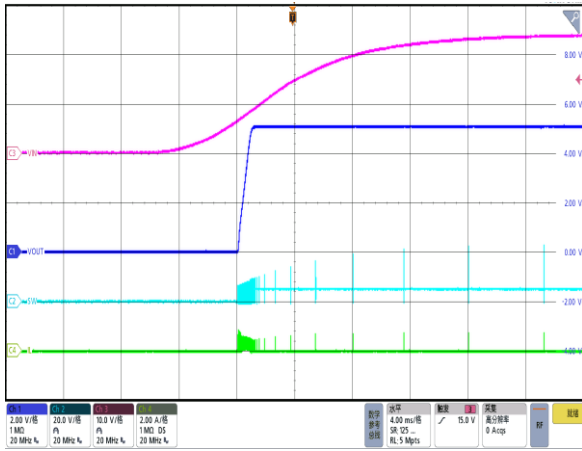


Figure 26. Power On by VIN, $I_{OUT}=0A$, PFM

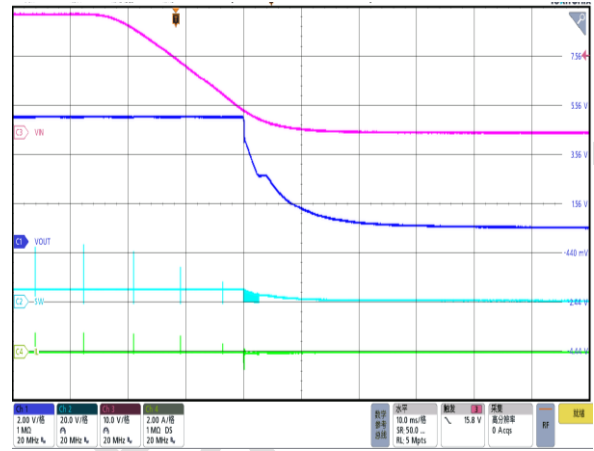


Figure 27. Power Off by VIN, $I_{OUT}=0A$, PFM

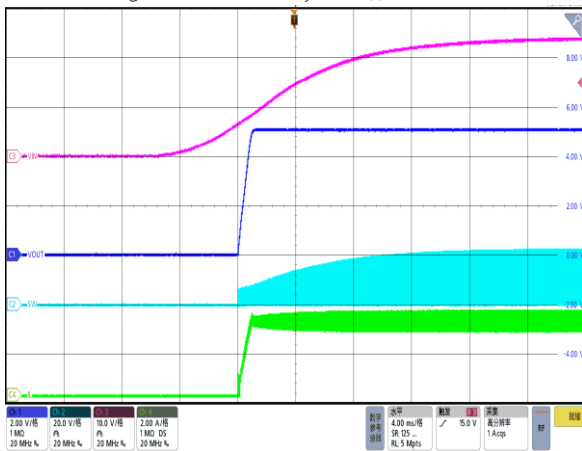


Figure 28. Power On by VIN, $I_{OUT}=3A$, PFM

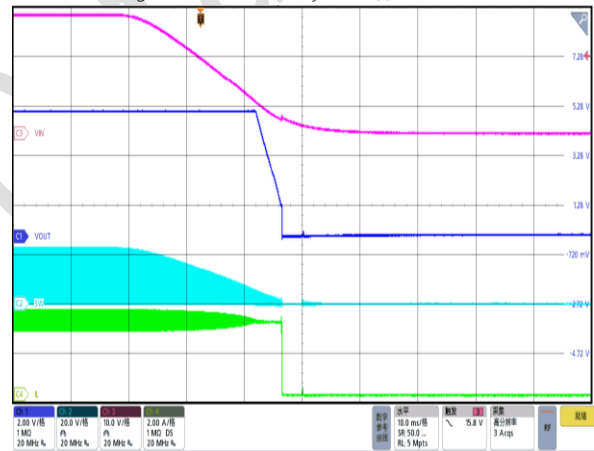


Figure 29. Power Off by VIN, $I_{OUT}=3A$, PFM

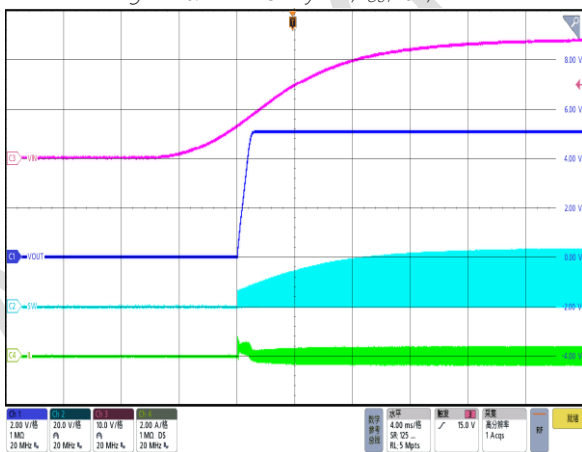


Figure 30. Power On by VIN, $I_{OUT}=0A$, FCCM

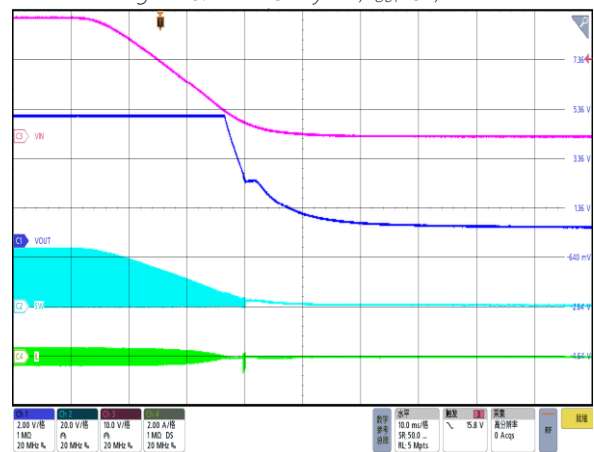


Figure 31. Power Off by VIN, $I_{OUT}=0A$, FCCM

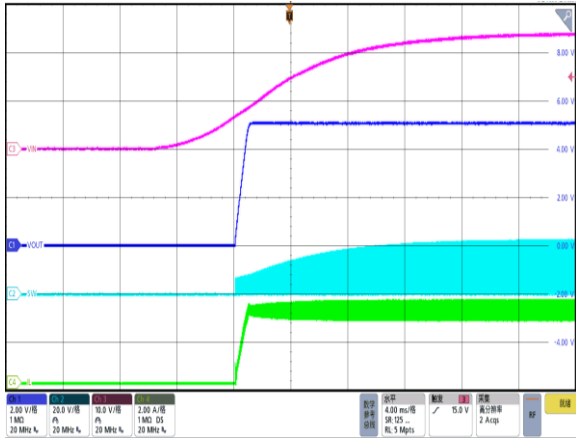


Figure 32. Power On by VIN, $I_{OUT}=3A$, FCCM

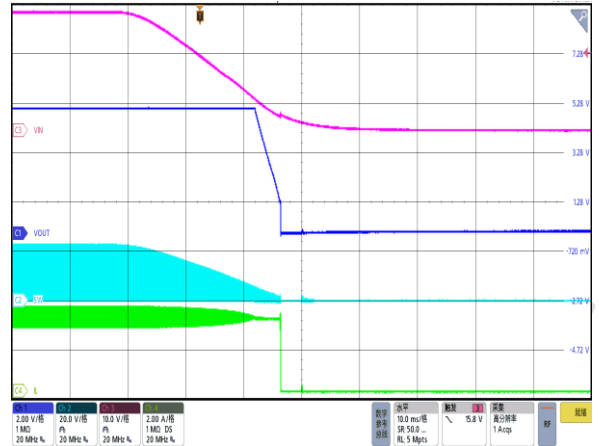


Figure 33. Power Off by VIN, $I_{OUT}=3A$, FCCM

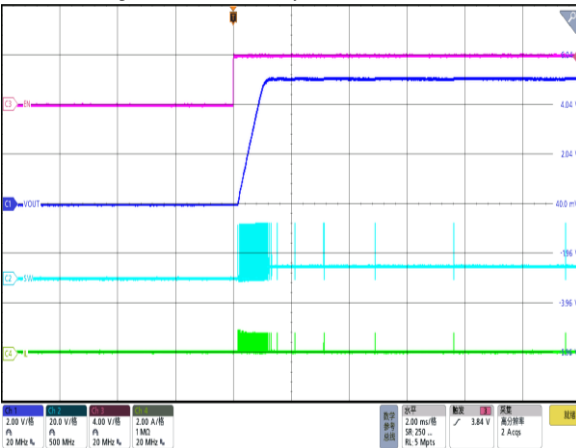


Figure 34. Power On by EN, $I_{OUT}=0A$, PFM

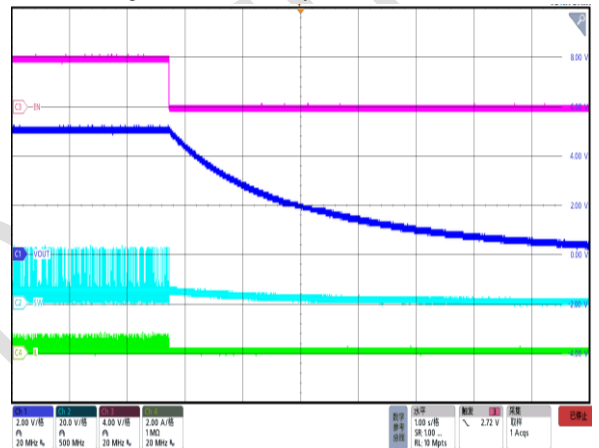


Figure 35. Power Off by EN, $I_{OUT}=0A$, PFM

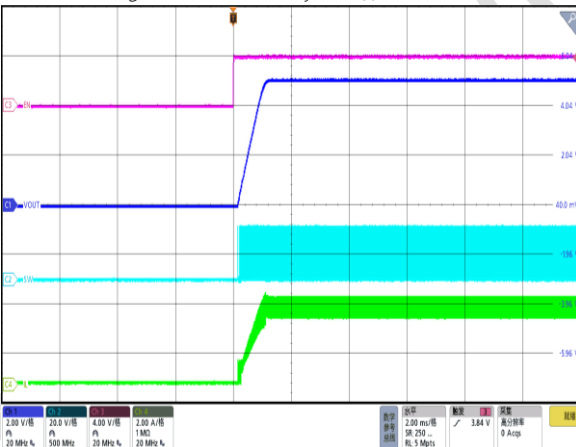


Figure 36. Power On by EN, $I_{OUT}=3A$, PFM

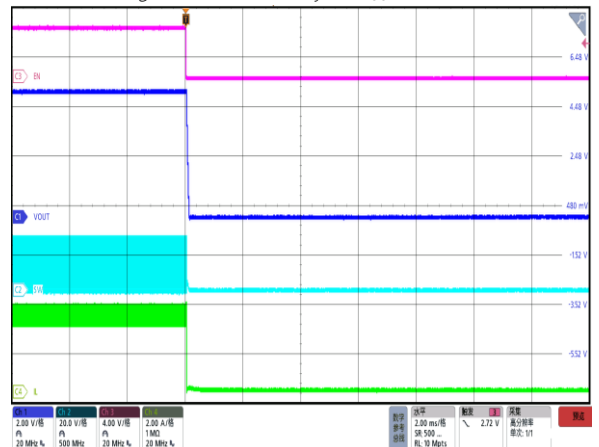


Figure 37. Power Off by EN, $I_{OUT}=3A$, PFM

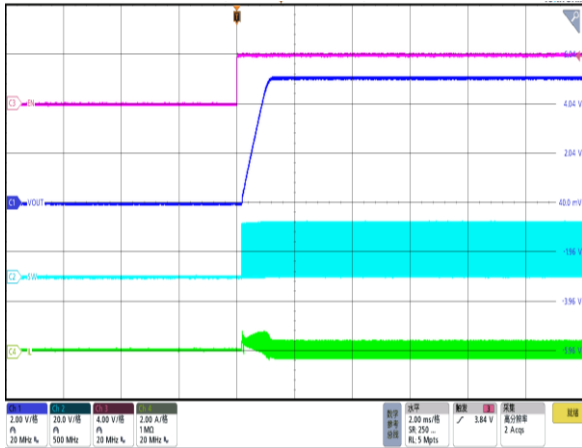


Figure 38. Power On by EN, $I_{OUT}=0A$, FCCM

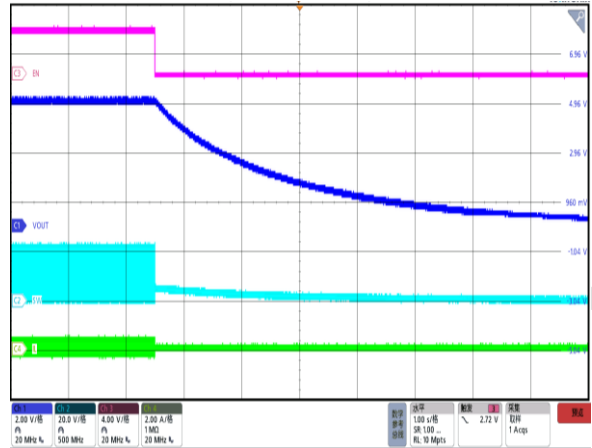


Figure 39. Power Off by EN, $I_{OUT}=0A$, FCCM

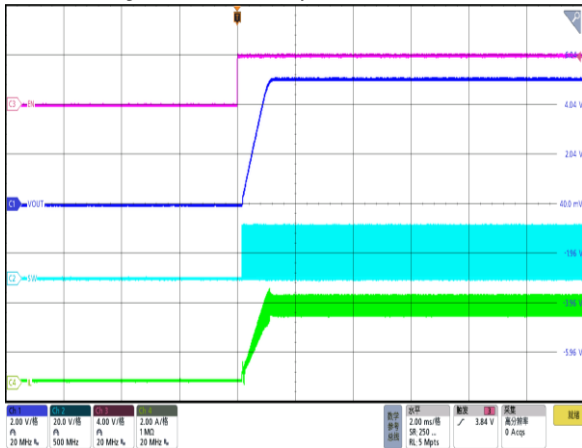


Figure 40. Power On by EN, $I_{OUT}=3A$, FCCM

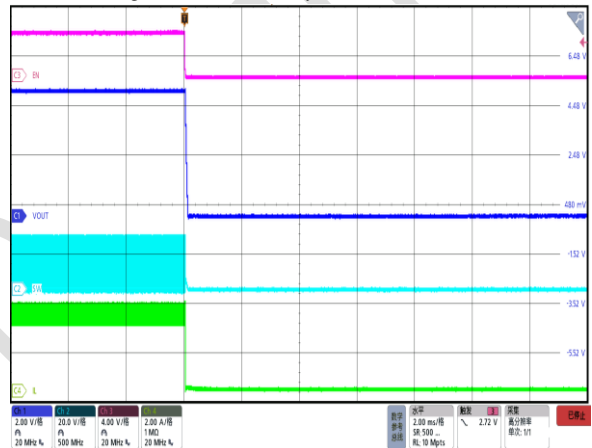


Figure 41. Power Off by EN, $I_{OUT}=3A$, FCCM

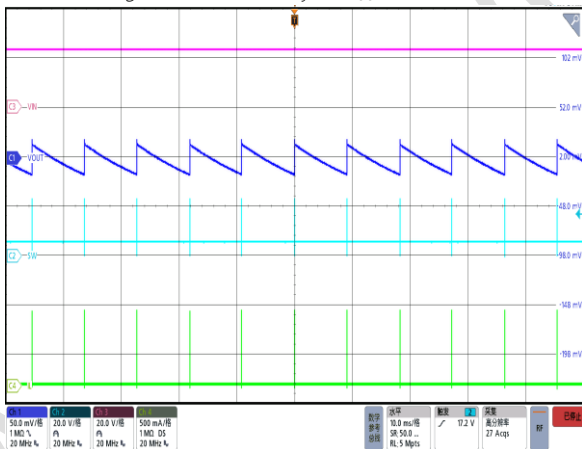


Figure 42. Switching Waveform, $I_{OUT}=0A$, PFM

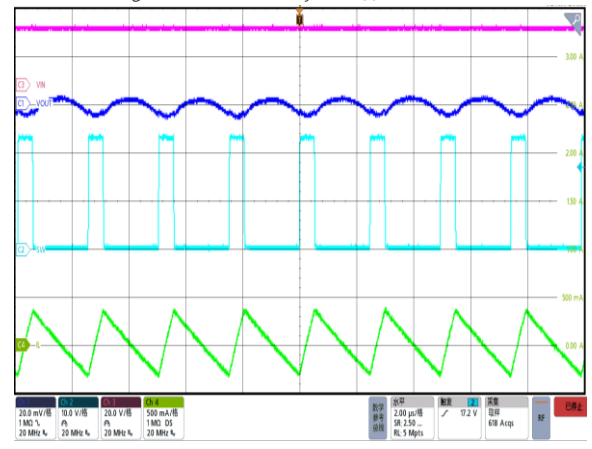


Figure 43. Switching Waveform, $I_{OUT}=0A$, FCCM

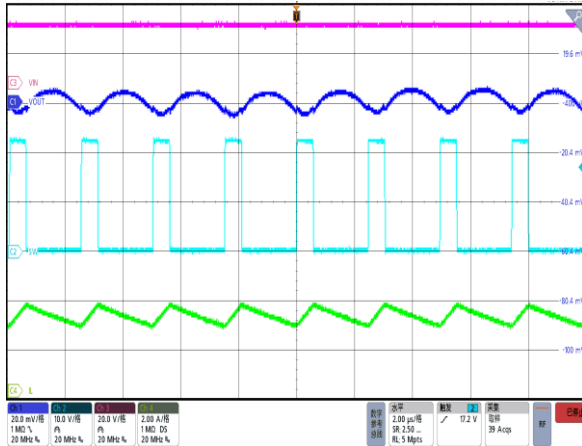


Figure 44. Switching Waveform, $I_{OUT}=3A$, PFM

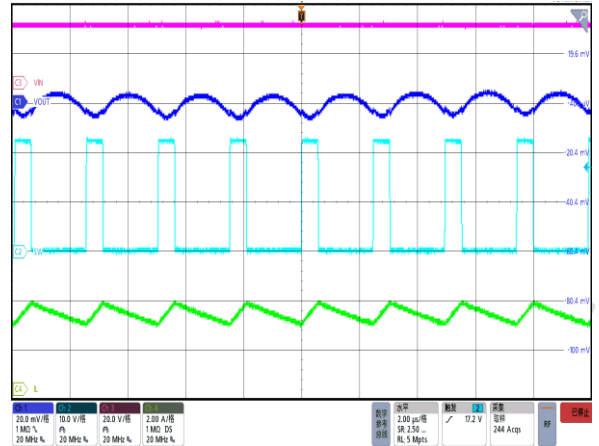


Figure 45. Switching Waveform, $I_{OUT}=3A$, FCCM

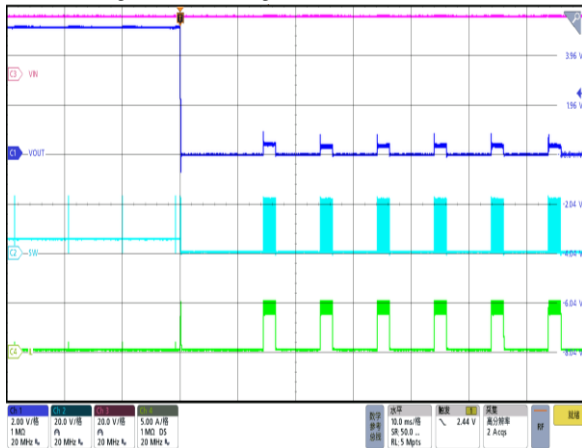


Figure 46. SCP Entry, $I_{OUT}=0A$, PFM

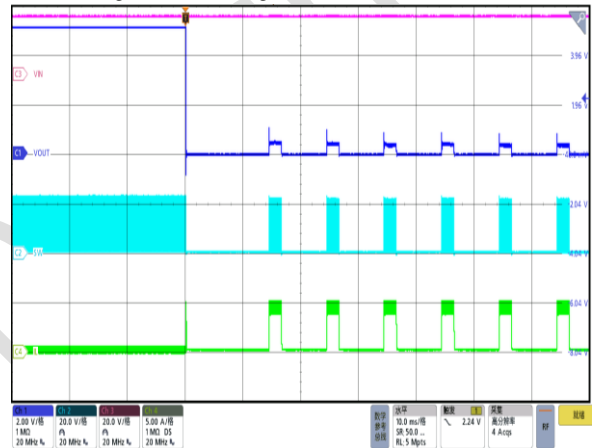


Figure 47. SCP Entry, $I_{OUT}=0A$, FCCM

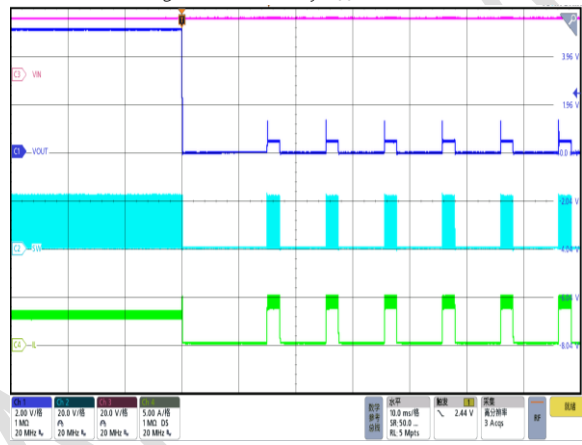


Figure 48. SCP Entry, $I_{OUT}=3A$, PFM

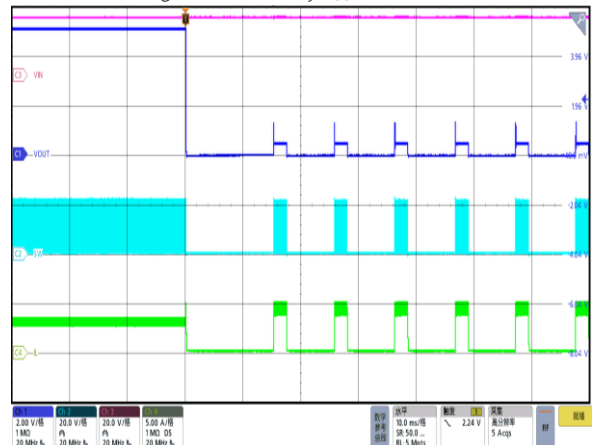


Figure 49. SCP Entry, $I_{OUT}=3A$, FCCM

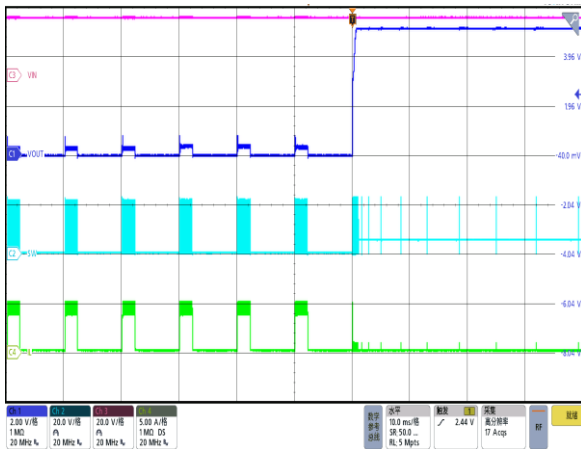


Figure 50. SCP Recovery, $I_{OUT}=0A$, PFM

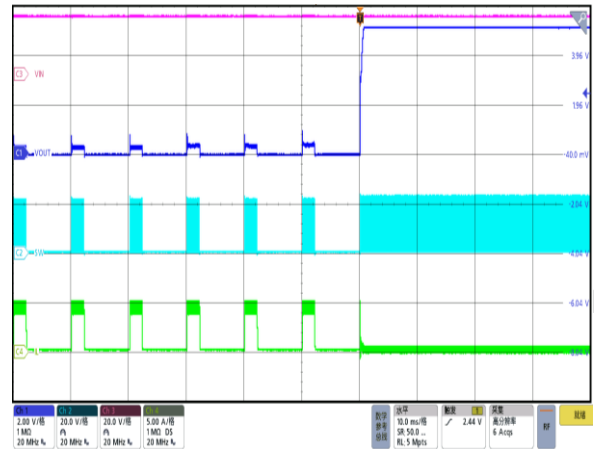


Figure 51. SCP Recovery, $I_{OUT}=0A$, FCCM

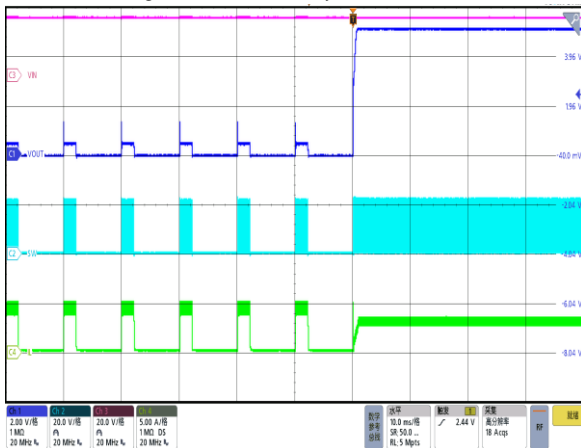


Figure 52. SCP Recovery, $I_{OUT}=3A$, PFM

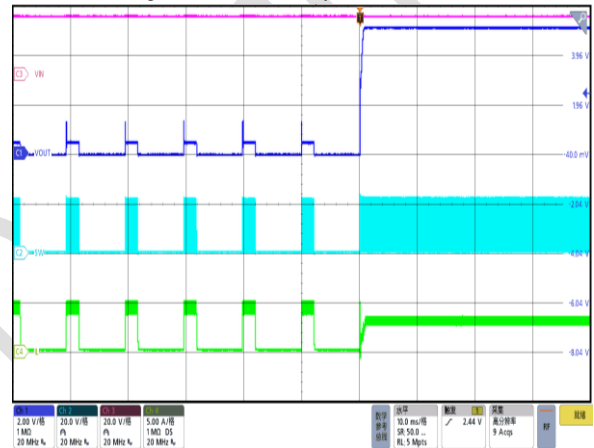


Figure 53. SCP Recovery, $I_{OUT}=3A$, FCCM

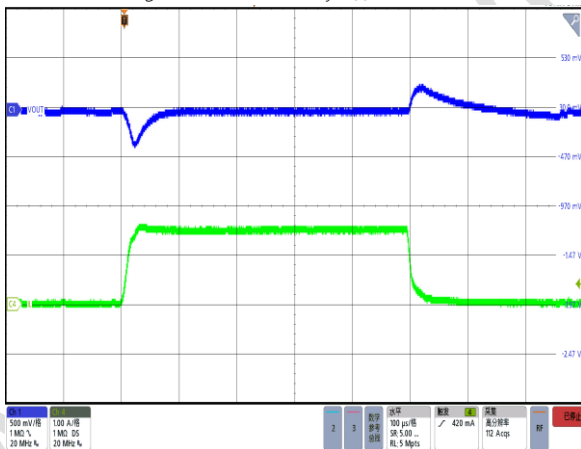


Figure 54. Load Transient, $I_{OUT}=0A$ to 1.5A, PFM

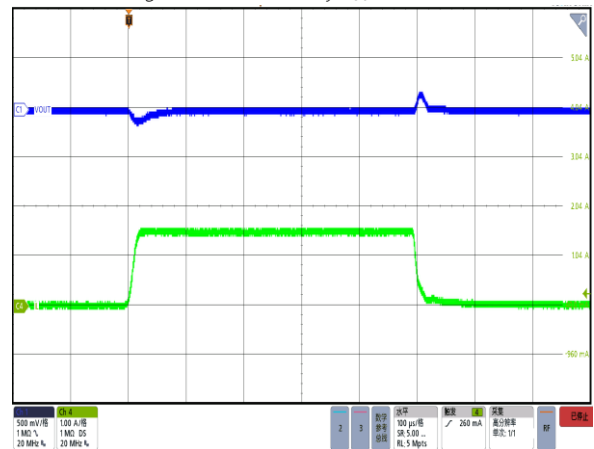


Figure 55. Load Transient, $I_{OUT}=0A$ to 1.5A, FCCM

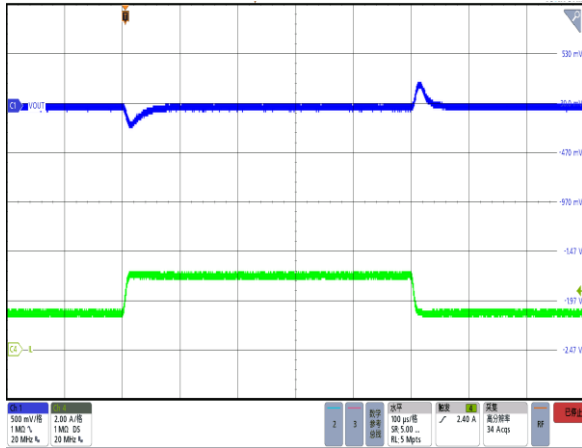


Figure 56. Load Transient, $I_{out}=1.5A$ to $3A$, PFM

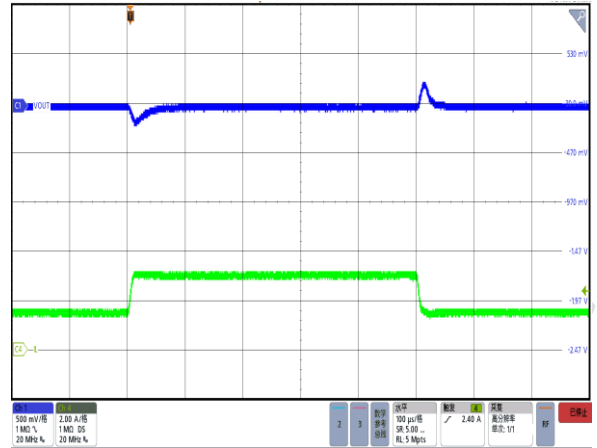


Figure 57. Load Transient, $I_{out}=1.5A$ to $3A$, FCCM

Analogwin Datasheet

FUNCTIONAL BLOCK DIAGRAM

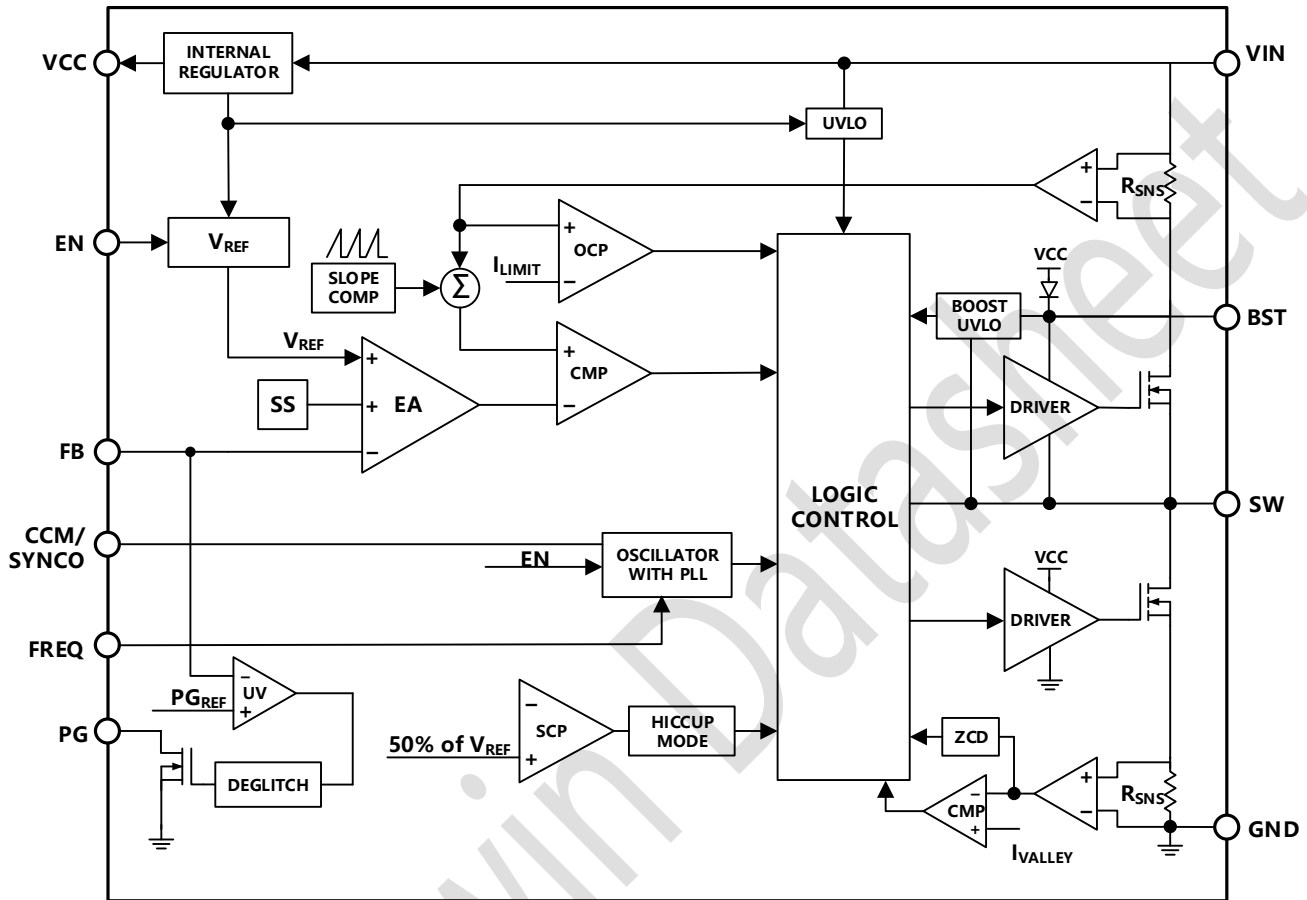


Figure 58. Functional Block Diagram

PRODUCT OVERVIEW

The AWK4573 is a synchronous step-down, DC-DC regulator with a high-side MOSFET and a low-side synchronous rectifier MOSFET. The AWK4573 operates a wide range of 3.4V to 60V input voltage and the device is capable of delivering up to 3A continuous current load. This converter is highly adaptable to Industrial and telecom environment applications which require high performance.

It employs peak-current-mode control to regulate the output voltage. In the light load conditions, the device provides selectable Pulse Frequency Modulation (PFM) for higher efficiency or Forced Continuous Conduction Mode (FCCM) for smaller output ripple. In the heavy load conditions, the device runs in the Pulse Width Modulation (PWM) mode at a constant frequency. The switching frequency is configured by the FREQ resistor. The regulator is internally compensated, which allows few external components and reduces design time.

The AWK4573's protection features include undervoltage lockout, over current protection, short-circuit protection, and thermal shutdown. Additional features include the following: low shutdown current; internal soft start; precision enable; Power good indication; synchronous output function; pre-biased start up.

PEAK CURRENT CONTROL

The AWK4573 uses fixed frequency peak current mode control architecture. The inductor current increases when the integrated high-side MOSFET turns on, and the high-side MOSFET turns off when the inductor peak current reaches the peak threshold set by the COMP voltage of the internal error amplifier, while the low side synchronous rectifier MOSFET turns on until the next cycle or the inductor current falls to zero.

The error amplifier of the AWK4573 adjusts the COMP voltage by comparing the voltage of the FB pin with the internal 0.8V reference. When the load current increases, the FB voltage drops below the internal reference. This causes the error amplifier to raise the COMP voltage, thereby increasing the inductor peak current until sufficient power is delivered to keep the output voltage in regulation. Meanwhile, the AWK4573 integrates slope compensation circuitry to avoid subharmonic oscillation when the duty cycle exceeds 50%.

OPERATING MODES

The AWK4573 features configurable Forced Continuous Conduction Mode (FCCM) and Pulse Frequency Modulation (PFM) mode. FCCM maintains a constant switching frequency (f_{sw}) and a small output ripple, but has low efficiency under light-load conditions. PFM mode is enabled when the CCM/SYNCO pin is floated, and it achieves high efficiency under light-load conditions. To force the device into FCCM, use a resistor between 10k Ω and 300k Ω to connect CCM/SYNCO to GND. The device cannot change modes once it is turned on; the desired mode must be selected before start-up.

In FCCM mode, the converter operates at a fixed frequency across a no-load to full-load range.

In PFM mode, the switching frequency (f_{sw}) scales down with the COMP voltage. As the output current (I_{out}) decreases, the feedback voltage rises, causing the COMP voltage to drop. When the COMP voltage reaches a low clamp threshold, the device enters PFM operation. Once in PFM mode, the output capacitor discharges, causing the output voltage to decrease. When the FB voltage drops below the reference voltage and the COMP

voltage rises above the low clamp threshold, the high-side power MOSFET turns on at the next clock pulse. After this clock, the COMP voltage drops again and is clamped, and PFM mode repeats. This control scheme improves efficiency by scaling down the frequency to reduce switching and gate driver losses while minimizing the input quiescent current. As I_{OUT} increases from light-load, both COMP voltage and f_{SW} rise. If I_{OUT} exceeds a critical level (the continuous current boundary), the inductor current becomes continuous, and the converter transitions from Discontinuous Conduction Mode (DCM) into Continuous Conduction Mode (CCM). In CCM, the switching frequency remains constant.

PRECISION ENABLE AND SHUTDOWN

The AWK4573 uses the EN pin to control start-up and shutdown. This input pin features a precision analog threshold of 1.47V. When a voltage on the EN pin is greater than 1.47V, the converter turns on; when the voltage falls to less than 1.14V, the converter shuts down. If the EN pin is driven by V_{IN} (or any voltage exceeding its absolute maximum rating), an external protection network is required. Connect a 100k Ω resistor from V_{IN} to EN, and clamp the EN pin to ground with a 5.6V Zener diode. To shut down the device, leave the EN pin floating; it is internally pulled low by a resistor (R_{EN}) to GND. The internal pull-down resistance is 3M Ω when the EN pin is driven high (enable active), and switches to 1.9M Ω when the EN pin is low (shutdown).

INTERNAL VCC REGULATOR

The VCC pin is the output of the internal regulator, which provides the bias for the internal circuits and MOSFET GATE drivers. It is recommended that a high-quality 1 μ F ceramic capacitor be connected from this pin to GND. It is not recommended to connect any external loads to the VCC pin.

BOOTSTRAP CIRCUITRY

The bootstrap voltage provides the gate drive power for high-side MOSFET. The bootstrap capacitor voltage is charged via a diode from V_{CC} when high-side MOSFET is off and low-side MOSFET is on, which generates a bootstrap voltage between the BST and SW pins. It is recommended that a 0.1 μ F, 10V ceramic capacitor be connected from BST pin to SW pin.

SYNCHRONOUS OUTPUT (SYNCO)

The AWK4573 has a SYNCO pin for synchronous output. During start-up, SYNCO remains low; once soft start (SS) is ready, it outputs a 180° phase-shifted clock relative to the internal oscillator. SYNCO's falling edge is a 180° phase shift from the rising edge of the internal oscillator. The synchronous output function allows two devices to operate at the same frequency, but 180° out of phase. This reduces the total input current ripple and allows for the use of a smaller input bypass capacitor.

SWITCHING FREQUENCY

The switching frequency of the AWK4573 is set by a single resistor (R_{FREQ}) connected between the FREQ pin and GND, placed close to the IC. The resistor value can be calculated from the following equation:

$$R_{FREQ}(k\Omega) = \frac{30000}{f_{SW}(kHz)}$$

For example, a 76.8kΩ resistor sets the switching frequency to 400kHz, a 28kΩ resistor sets the frequency to 1MHz, and a 12.1kΩ resistor sets the switching frequency to 2.2MHz. A bench test may be required to fine-tune the calculated resistance. Table 7 shows the typical relationship between f_{sw} and R_{FREQ} .

Table 7. SWITCHING FREQUENCY vs. R_{FREQ}

$R_{FREQ}(k\Omega)$	$f_{sw}(kHz)$	$R_{FREQ}(k\Omega)$	$f_{sw}(kHz)$
100	300	28	1000
91.9	330	24.3	1150
82.5	360	22	1250
76.8	400	20	1350
68.1	430	18.2	1500
61.9	475	16.2	1650
56	520	15	1750
47	600	14	1900
39	700	13	2050
34.8	800	12.1	2200
30	940		

SPREAD SPECTRUM MODULATION

The AWK4573 implements the Spread Spectrum Modulation (SSM) to reduce EMI for most automotive applications. The SSM circuitry periodically modulates the switching frequency upward from the configured value using a triangular profile; the maximum frequency increase is approximately 18% relative to the programmed frequency (typical at $f_{sw} = 400kHz$). The modulation frequency is approximately 3kHz. The modulation parameters are factory-fixed and apply only to the AWK4573AA.

INTERNAL SOFT START (SS) AND PREBIAS SOFT START

The AWK4573 features integrated reference-based soft start circuitry to limit the output voltage rise time and prevent output voltage overshoot and inrush current during startup. During Soft Start (SS), V_{OUT} ramps up at a controlled slew rate once EN goes high. The device uses the lowest voltage among the internal reference voltage, the internal soft-start voltage, and the SS pin voltage as the reference to which the error amplifier regulates the FB voltage. If the soft-start voltage (V_{SS}) drops below the internal reference voltage (V_{REF}), V_{SS} overrides V_{REF} as the EA reference. The soft start completes when V_{SS} exceeds V_{REF} of 0.8V. Once SS is complete, the AWK4573 enters steady state operation.

The soft start time is internally fixed at 0.9ms. If V_{OUT} shorts to GND, V_{FB} is pulled low and V_{SS} discharges towards GND. Once the short is removed and the AWK4573 returns to a normal state, the device initiates another SS.

If the output voltage is pre-biased at an initial voltage before the AWK4573 start up, neither the high-side MOSFET nor the low-side MOSFET of the device turns on to initiate switching until the internal reference voltage has reached V_{FB} . The output is not pulled low during the pre-biased startup condition.

POWER GOOD FUNCTION

The Power good pin is an open-drain output, which indicates that the FB pin voltage is within regulation and can be used to simplify the sequencing. It is recommended that the PG pin be tied through an external pullup resistor of about 100k Ω to a suitable logic supply if this function is needed; if not, the PG pin must be left floating. The PG internal circuitry monitors the FB pin voltage and compares it to the rising and falling thresholds. This operation is illustrated in Figure 59.

The PG pin is pulled low when any of the following events occurs: the output voltage falls below the FB falling threshold, exceeds the FB rising threshold, UVLO, OVP, current limit, thermal shutdown, or a disabled state.

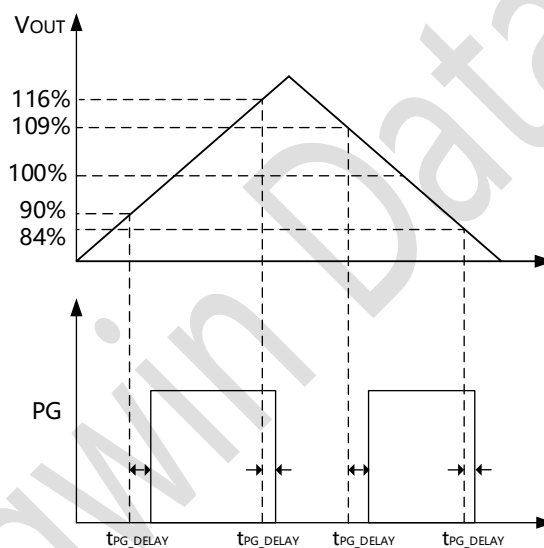


Figure 59. PG-timing behavior

UNDERVOLTAGE LOCKOUT (UVLO)

The AWK4573 features undervoltage lockout (UVLO) protection to prevent issues from power-on glitches. When the EN pin is enabled, once the V_{IN} pin voltage exceeds the UVLO rising threshold, the internal circuitry is activated and the soft start period is initiated. If V_{IN} drops below the falling threshold, the device shuts down. V_{IN} UVLO is a non-latching protection.

OVER CURRENT PROTECTION AND SHORT CIRCUIT PROTECTION

The AWK4573 implements over current protection with cycle-by-cycle limiting of the inductor peak current and valley current to prevent current runaway during heavy loads or an output hard short. Cycle-by-cycle current limit is used for overloads, while hiccup mode is used for hard short circuits. The internal sensing circuitry monitors the high-side MOSFET current during its on-time. If the high-side MOSFET current exceeds the 5.4A peak current-limit threshold, it turns off immediately. The low-side MOSFET turns on, and the current

goes through it, which is also monitored. The low-side MOSFET is kept on until the inductor current falls below the 3A valley current limit threshold.

If a short circuit occurs, the AWK4573 reaches its peak current limit, and V_{OUT} drops until, after soft start completion, V_{FB} falls below 50% of V_{REF} . The device triggers Short-Circuit Protection, and enters hiccup mode. In hiccup mode, the high-side and low-side MOSFETS are both turned off before the AWK4573 attempts to restart. If the over current or short circuit fault is removed, the AWK4573 recovers to normal operation. Otherwise, the hiccup cycle repeats, protecting the device from overheating, excessive power dissipation under heavy load conditions, and potential damage.

NEGATIVE CURRENT LIMIT PROTECTION

The AWK4573 features a 1.2A negative current limit threshold. If the inductor current (I_L) drops below the negative current limit, the low-side MOSFET turns off and the high-side MOSFET turns on. This prevents the negative current from becoming too negative and potentially damaging the components.

THERMAL SHUTDOWN

The AWK4573 monitors the die temperature. If the junction temperature exceeds 170°C, the internal thermal shutdown circuitry turns off the regulator, stops the MOSFET switching, pulls down the SS. Thermal shut down is a non-latching protection. When the junction temperature falls below to 145°C, the part automatically resumes normal operation with soft start.

LOW-DROPOUT (LDO) MODE

When the voltage difference between V_{IN} and V_{OUT} is low, the AWK4573 operates at a duty cycle as close to 100% as possible, as long as the voltage between BST and SW exceeds 2.25V. When the voltage from BST to SW drops below 2.25V, the high-side MOSFET turns off and low-side MOSFET turns on to recharge bootstrap capacitor. If V_{IN} drops (bringing it close to V_{OUT}), the high-side MOSFET continues to operate as approaching to 100% duty as possible to maintain output regulation, unless the voltage between BST and SW falls below 2.25V.

During slow power-up and power-down, the high-side MOSFET off-time approaches its the minimum value, allowing the output voltage to closely track the input voltage ramping down. The effective duty cycle during regulator dropout is primarily influenced by the voltage drops across the power MOSFET, inductor resistance, low-side diode, and PCB resistance.

TYPICAL APPLICATION CIRCUIT

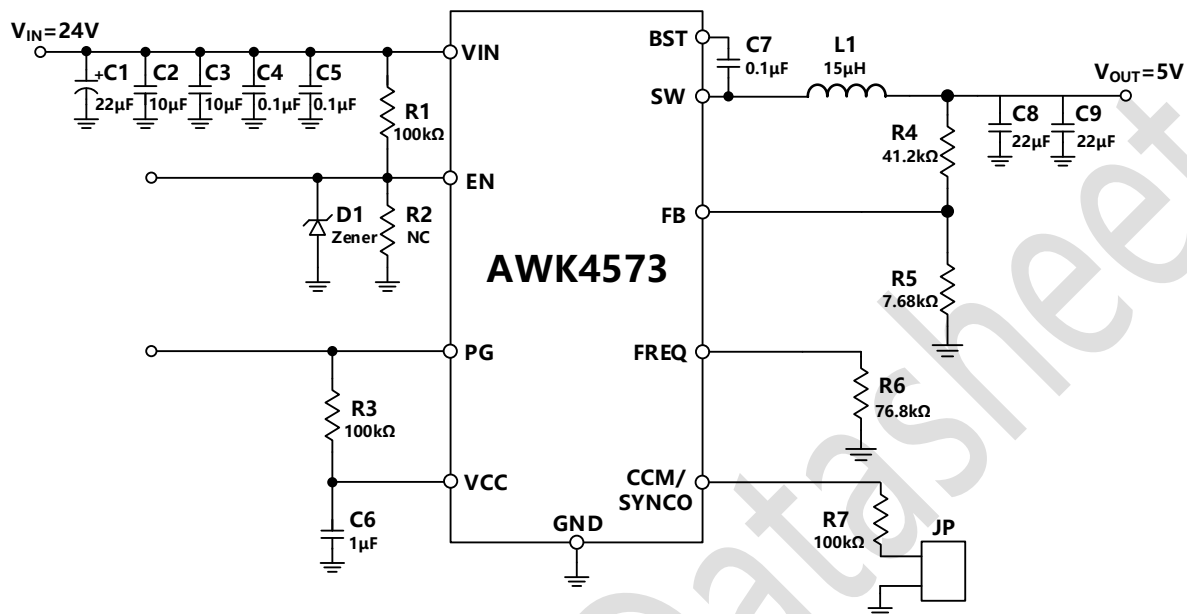


Figure 60. Typical Application Circuit (400kHz)

APPLICATION INFORMATION

Component selection steps are described in this section based on the example specifications listed in Table 8. The schematic of this design example is shown in Figure 60. Typical Application Circuit (400kHz).

Table 8. Parameter of Design Example

Parameter	Description
Input Voltage	$V_{IN} = 24V$
Output Voltage	$V_{OUT} = 5V$
Output Current	$I_{OUT} = 3A$
Switching Frequency	$f_{SW} = 400kHz$
Output Ripple	$\Delta V_{OUT_RIPPLE} = 20mV$
Load Transient	$\pm 5\%$, 1.5A to 3A

INPUT CAPACITOR SELECTION

The step-down converter has a discontinuous input current; therefore, it requires an input capacitor to supply the AC current component while maintaining a stable DC voltage at V_{IN} . Ceramic capacitors with X5R or X7R dielectrics are strongly recommended because of the low ESR and low temperature coefficients. To filter the high frequency switching noise, it is recommended to use a lower-value capacitor (0.1 μF) in an 0603 package size. Place the input capacitor as close as possible to the Vin pin. For most applications, a 22 μF capacitor is sufficient. For higher V_{OUT} , use a 47 μF capacitor to improve system stability.

The voltage rating of the input capacitor must be greater than the maximum input voltage. The input capacitor value is a function of the source impedance. A bulk capacitor is needed if the source impedance is too high. Make sure that the ripple current rating does not exceed the converter's maximum input ripple current, calculated from the following equation:

$$I_{C_{IN_RMS}} = I_{OUT} \times \sqrt{D \times (1-D)}$$

The worst-case condition occurs at $V_{IN} = 2 \times V_{OUT}$, where

$$I_{C_{IN_RMS}} = \frac{I_{OUT}}{2}$$

For simplification, choose a C_{IN} with an RMS current rating greater than half of the maximum load current.

Ensure that the voltage rating of the input capacitor is greater than the maximum input voltage. The input voltage ripple caused by the capacitance can be calculated from the following equation:

$$\Delta V_{IN} = \frac{I_{OUT}}{f_{SW} \times C_{OUT}} \times D \times (1-D)$$

OUTPUT VOLTAGE SETTING

The output voltage of the AWK4573 is set by an external resistor divider. Use the following equation to calculate resistor values:

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R_{TOP}}{R_{BOT}}\right)$$

Where:

V_{REF} is the typical reference value, 0.8V.

Table 9 lists the recommended resistor divider values of R_{TOP} , R_{BOT} for the common output voltages.

Table 9. Recommended Resistor Values for Common Output Voltages

V_{OUT}(V)	R_{TOP}(kΩ)	R_{BOT}(kΩ)
3.3	41.2	13
5.0	41.2	7.68
8	41.2	4.53
12	41.2	2.98

INDUCTOR SELECTION

The inductor value is determined by the switching frequency, input voltage, output voltage, and inductor ripple current. For the highest efficiency, choose an inductor with a low DC resistance. The performance of the inductor affects the transient behavior, efficiency, and loop stability. Using a larger inductor value reduces the output ripple current and reduces the output voltage ripple, and leads to better efficiency, but it leads to

slower transient behavior. A smaller inductor value offers fast transient behavior, but it leads to larger inductor ripple current and decreases efficiency.

The inductor value can be calculated by the following equation:

$$L = \frac{(V_{IN} - V_{OUT}) \times D}{\Delta I_L \times f_{SW}}$$

where:

V_{IN} is the input voltage.

V_{OUT} is the output voltage.

D is the duty cycle ($D = \frac{V_{OUT}}{V_{IN}}$)

f_{SW} is the switching frequency.

ΔI_L is the inductor ripple current, which is, for the most applications, typically between 20% and 40% of the maximum load current.

The peak inductor current, I_{PEAK} is calculated by the following equation:

$$I_{PEAK} = I_{LOAD} + \frac{\Delta I_L}{2}$$

The saturation current of the inductor must be higher than the device's peak current limit, and RMS current must also not be exceeded, as the following equation:

$$I_{RMS} = \sqrt{(I_{OUT})^2 + \frac{\Delta I_L^2}{12}}$$

OUTPUT CAPACITOR SELECTION

The output capacitor determines the output ripple, stores energy to meet transient load demands, and affects the loop stability of the regulator. The selection of the output capacitor is based on two factors. One factor is the voltage ripple caused by the inductor ripple current across the ESR of the output capacitor; the other is the voltage ripple due to the charging and discharging of the output capacitor by the inductor ripple current. Ceramic capacitors are strongly recommended for their small size and low ESR. Electrolytic and polymer capacitors may also be used. The output voltage ripple can be calculated by the following equation:

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_{SW} \times L} \times (1 - D) \times \left(R_{ESR} + \frac{1}{8 f_{SW} \times C_{OUT}} \right)$$

where:

R_{ESR} is the equivalent series resistance of C_{OUT} in ohms (Ω).

For ceramic capacitors, the output voltage ripple can be calculated by the following equation:

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times f_{SW}^2 \times L \times C_{OUT}} \times (1 - D)$$

Additionally, temperature and DC bias voltage can both affect the capacitance. Ceramic capacitors can lose most of the capacitance at rated voltage. Therefore, use capacitors with X5R or X7R, and leave enough margin on the voltage rating to ensure adequate effective capacitance and to meet both load transient performance and output ripple. A minimum capacitance value of $2 \times 22\mu\text{F}$ is recommended. To compensate for capacitance loss under bias voltage, select a capacitor with a voltage rating at least twice the maximum applied voltage.

SETTING VIN UNDER-VOLTAGE LOCKOUT (UVLO)

The AWK4573 has an internal, fixed UVLO threshold. The rising threshold is 3.4V, and the falling threshold is about 2.9V. The device has a precision enable input that can be used to configure the UVLO threshold of the input voltage, which is shown in the Figure 61.

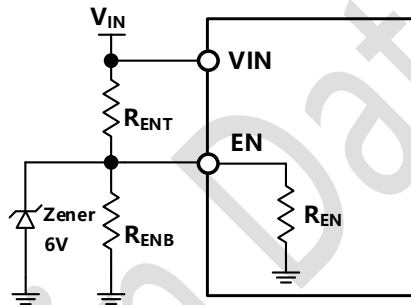


Figure 61. Configure the VIN UVLO

If enable (EN) control is on, then $R_{EN} = 3\text{M}\Omega$. If EN control is off, then $R_{EN} = 1.9\text{M}\Omega$. When EN is rising, the UVLO threshold can be calculated by the following equation:

$$V_{IN_UV_RISING} = \left(1 + \frac{R_{ENT}}{1.9\text{M}\Omega // R_{ENB}}\right) \times V_{EN_RISING}$$

When EN is falling, the UVLO threshold can be calculated by the following equation:

$$V_{IN_UV_FALLING} = \left(1 + \frac{R_{ENT}}{3\text{M}\Omega // R_{ENB}}\right) \times V_{EN_FALLING}$$

If the EN pin is connected to VIN through a resistor, note that the EN pin's maximum voltage rating is 6V. Therefore, add a 5.6V Zener diode between EN and GND. Additionally, R_{ENT} must be large enough to limit the current flowing into the EN pin to below $100\mu\text{A}$.

BOOTSTRAP (BST) RESISTOR AND CAPACITOR SELECTION

A resistor (R_{BST}) in series with C_{BST} can reduce the SW node's rising rate and voltage spikes. This improves EMI performance and reduces voltage stress at high V_{IN} . A higher resistance is better for SW spike reduction, but can compromise efficiency. To make a tradeoff between EMI and efficiency, it is recommended to keep R_{BST} below 20Ω . The recommended C_{BST} value is $0.1\mu\text{F}$.

LAYOUT RECOMMENDATION

The quality of the PCB layout is essential for the performance of the AWK4573. Bad PCB layout can degrade the output regulation, the EMI and EMC performance. For the best performance the AWK4573, use a four-layer board with the copper thickness for the four layers, starting from the top as: 2oz/1oz/1oz/2oz. Refer to Figure 62 and follow the guidelines.

1. Place the input capacitor, inductor, and output capacitor as close as possible to the IC, and use the short trace.
2. Place bypass capacitor for VCC close to the VCC pin.
3. Keep the switching loop as small as possible.
4. Keep VIN, VOUT, GND paths as short and wide as possible.
5. Place the feedback divider as close as possible to the FB pin to prevent noise pickup.
6. Place enough PCB area and use multiple vias to connect the power planes to the internal layer for proper heat sinking.

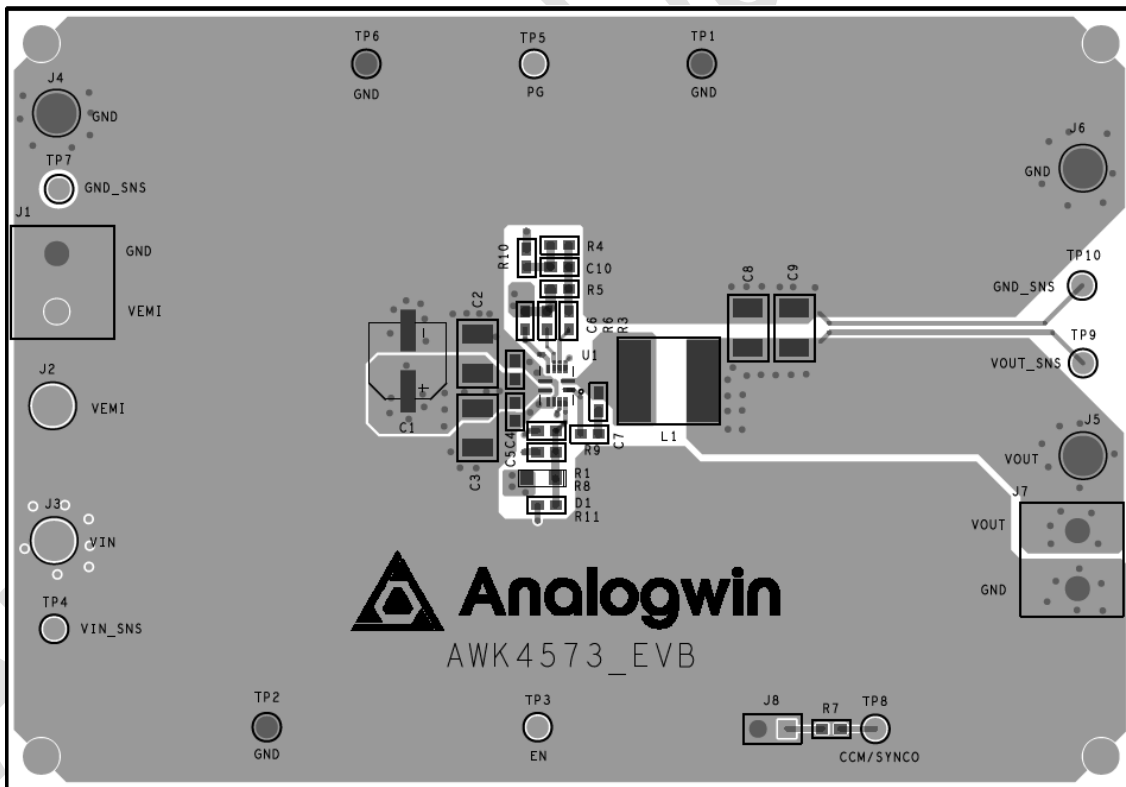


Figure 62. EVM TOP Layer Example

PACKAGE INFORMATION

PACKAGE TOP MARKING

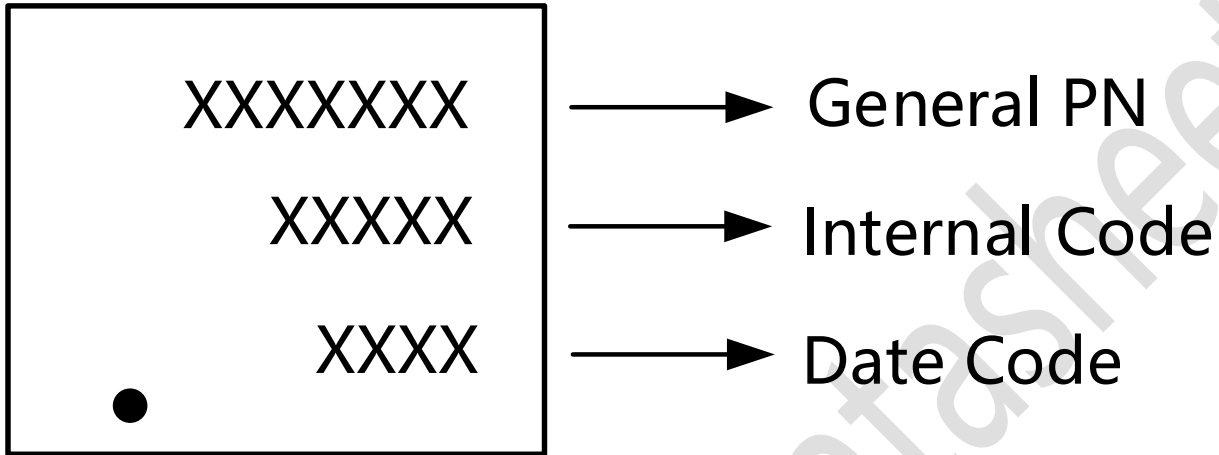


Figure 63. Package Top Marking

TAPE AND REEL BOX INFORMATION

DEVICE	PACKAGE TYPE	PACKAGE DRAWING	PINS	SPQ
AWK4573	QFN 2.5×3-12	TH	12	3000

TAPE AND REEL INFORMATION

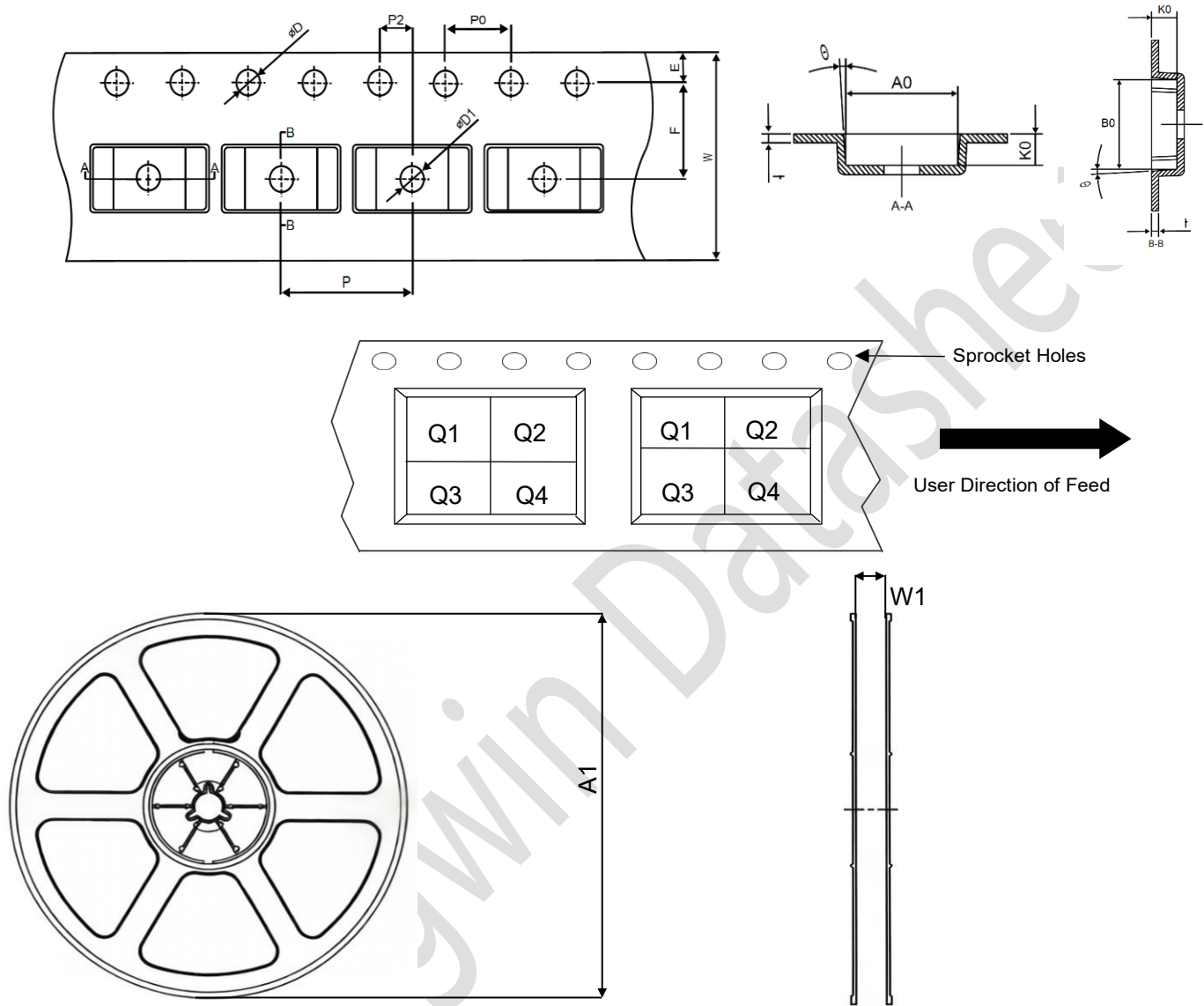


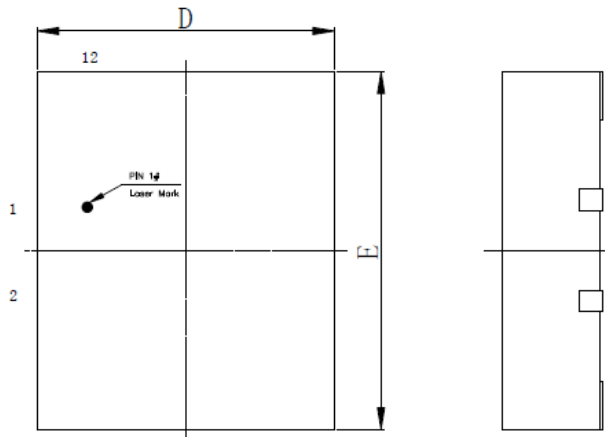
Figure 64. TAPE and Reel Information

DIMENSIONS AND PIN1 ORIENTATION

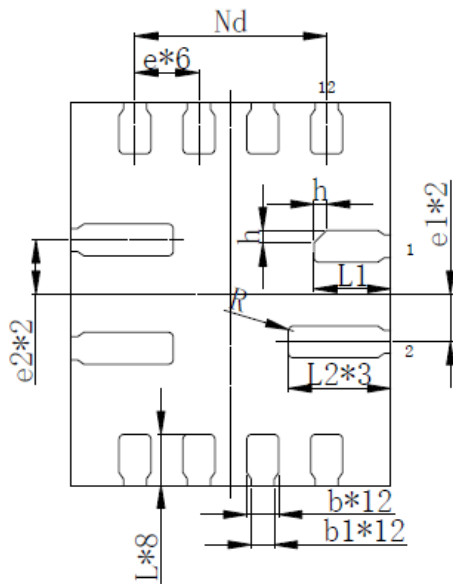
Device	Package Type	E (mm)	F (mm)	P2 (mm)	D (mm)	D1 (mm)	P0 (mm)	W (mm)	W1 (mm)	P (mm)	A0 (mm)	A1 (mm)	B0 (mm)	K0 (mm)	t (mm)	Pin1 Quadrant	Quantity
AWK4573THR	QFN 2.5×3-12	1.75	5.50	2.00	1.55	1.10	4.00	12.0	12.8	8.00	2.80	180	3.3	1.20	0.25	Q1	3000

All dimensions are nominal

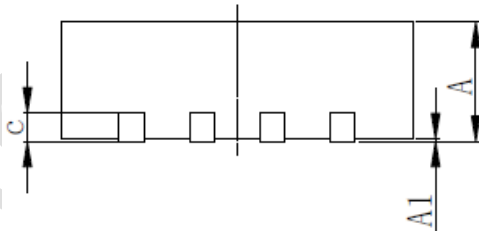
PACKAGE OUTLINES



TOP VIEW



BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.80	0.85	0.90
A1	0	0.02	0.05
b	0.20	0.25	0.30
b1	0.18REF		
c	0.203REF		
D	2.40	2.50	2.60
e	0.50BSC		
e1	0.375BSC		
e2	0.425BSC		
E	2.90	3.00	3.10
Nd	1.50BSC		
L	0.35	0.40	0.45
L1	0.55	0.60	0.65
L2	0.75	0.80	0.85
h	0.05	0.10	0.15
R	0.04REF		

Figure 65. QFN 2.5x3-12 Package

ORDERING INFORMATION

Device	Order Part No.	Spread Spectrum	Package	QTY
AWK4573	AWK4573AATHR	Yes	QFN 2.5×3-12, Pb-Free	3000/Reel
	AWK4573ABTHR	No	QFN 2.5×3-12, Pb-Free	3000/Reel

REVISION HISTORY

Version	Date	Descriptions
Rev. 0.5	02/2026	Initial version
Rev. 1.0	04/2026	Changes to Specifications. Changes to Electrical Specifications. Changes to Typical Characteristics. Changes to Typical Performance Characteristics. Changes to Ordering Information.